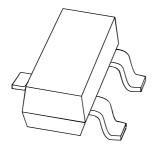
DISCRETE SEMICONDUCTORS

DATA SHEET



PMBTA56 PNP general purpose transistor

Product data sheet Supersedes data of 1999 Apr 09 2004 Jan 09



PNP general purpose transistor

PMBTA56

FEATURES

• High current (max. 500 mA)

• Low voltage (max. 80 V).

APPLICATIONS

 General purpose switching and amplification, e.g. telephony and professional communication equipment.

DESCRIPTION

PNP transistor in a SOT23 plastic package. NPN complement: PMBTA06.

MARKING

TYPE NUMBER	MARKING CODE ⁽¹⁾
PMBTA56	*2G

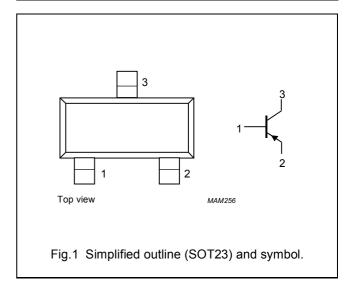
Note

1. * = p : Made in Hong Kong.* = t : Made in Malaysia.

* = W : Made in China.

PINNING

PIN	DESCRIPTION
1	base
2	emitter
3	collector



ORDERING INFORMATION

TYPE		PACKAGE				
NUMBER	NAME	DESCRIPTION VERSION				
PMBTA56	_	plastic surface mounted package; 3 leads	SOT23			

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	PARAMETER CONDITIONS			
V _{CBO}	collector-base voltage	open emitter	_	-80	V
V_{CEO}	collector-emitter voltage	open base	_	-80	V
V _{EBO}	emitter-base voltage	open collector	_	- 5	V
I _C	collector current (DC)		_	-500	mA
I _{CM}	peak collector current		_	-1	Α
I _{BM}	peak base current		_	-200	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C; note 1	_	250	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T _{amb}	operating ambient temperature		-65	+150	°C

Note

1. Transistor mounted on an FR4 printed-circuit board.

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THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-a)}	thermal resistance from junction to ambient	note 1	500	K/W

Note

1. Transistor mounted on an FR4 printed-circuit board.

CHARACTERISTICS

 T_{amb} = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	PARAMETER CONDITIONS			
I _{CBO}	collector cut-off current	$I_E = 0$; $V_{CB} = -80 \text{ V}$	_	- 50	nA
I _{EBO}	emitter cut-off current	$I_C = 0$; $V_{EB} = -5 \text{ V}$	_	-50	nA
h _{FE}	DC current gain	$I_C = -10 \text{ mA}; V_{CE} = -1 \text{ V}$	100	_	
		$I_C = -100 \text{ mA}; V_{CE} = -1 \text{ V}$	100	-	
V _{CEsat}	collector-emitter saturation voltage	$I_C = -100 \text{ mA}; I_B = -10 \text{ mA}$	_	-250	mV
V_{BE}	base-emitter voltage	$I_C = -100 \text{ mA}; V_{CE} = -1 \text{ V}$	_	-1.2	V
f _T	transition frequency	$I_C = -100 \text{ mA}; V_{CE} = -1 \text{ V};$ f = 100 MHz	50	_	MHz

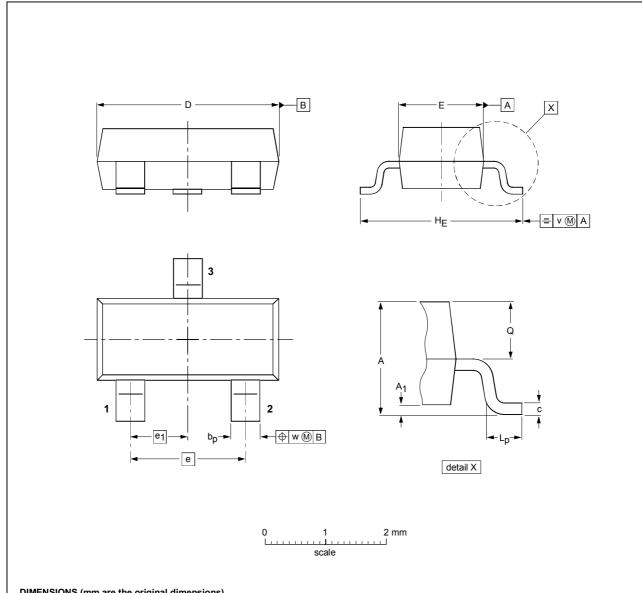
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PACKAGE OUTLINE

Plastic surface-mounted package; 3 leads

SOT23



UNIT	Α	A ₁ max.	bp	С	D	E	е	e ₁	HE	Lp	Q	v	w
mm	1.1 0.9	0.1	0.48 0.38	0.15 0.09	3.0 2.8	1.4 1.2	1.9	0.95	2.5 2.1	0.45 0.15	0.55 0.45	0.2	0.1

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT23		TO-236AB				-04-11-04 06-03-16

PNP general purpose transistor

PMBTA56

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

- 1. Please consult the most recently issued document before initiating or completing a design.
- 2. The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

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For sales offices addresses send e-mail to: salesaddresses@nxp.com

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